

**LED Gate Driver IC**

**Features**

- Max. Operating Voltage 5.5V
- Integrated With Four 80mΩ High Side MOSFETs and a 2-4 Decoder, It Can Support 8 or 16 Channels Scanning By Multi ICs Cascade
- Max. 5A Current
- De-ghost Function
- Fast Turn-on & Turn-off at Bus to Output
- OTP Function (Over Temperature Protection)
- SSOP-16 and TQFN3×3-16 Packages
- Solution of 1<sup>st</sup> dim line and LED coupling
- Channel holding at turn-off

**General Description**

The SPL5013C has 4 channels output for dynamic LED panel application; it is easy to supports 1/8 or 1/16 duty through multi-chips cascade. SPL5013C has fast turn off time for the de-ghost function. After the de-ghosting period, SPL5013C will hold at fixed level for the solution of 1<sup>st</sup> dim line/LED coupling, also to prevent damage LED

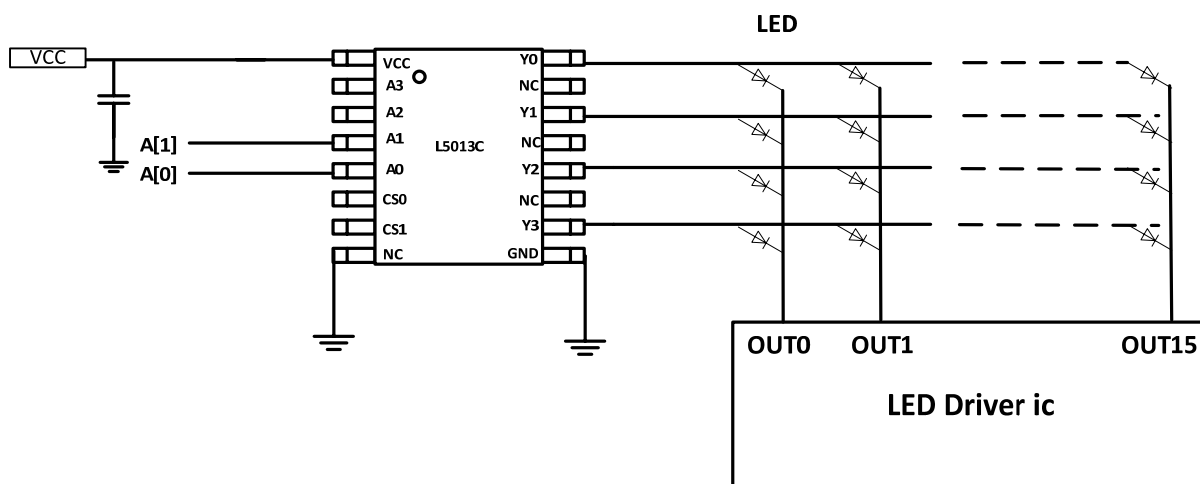
The device integrates some protection features, including OTP. The OTP function shuts down the outputs when the junction temperature rises beyond 150°C and will automatically turn on the outputs when the temperature drops by 40°C.

The device is available in lead free SSOP-16 and TQFN3×3-16 package.

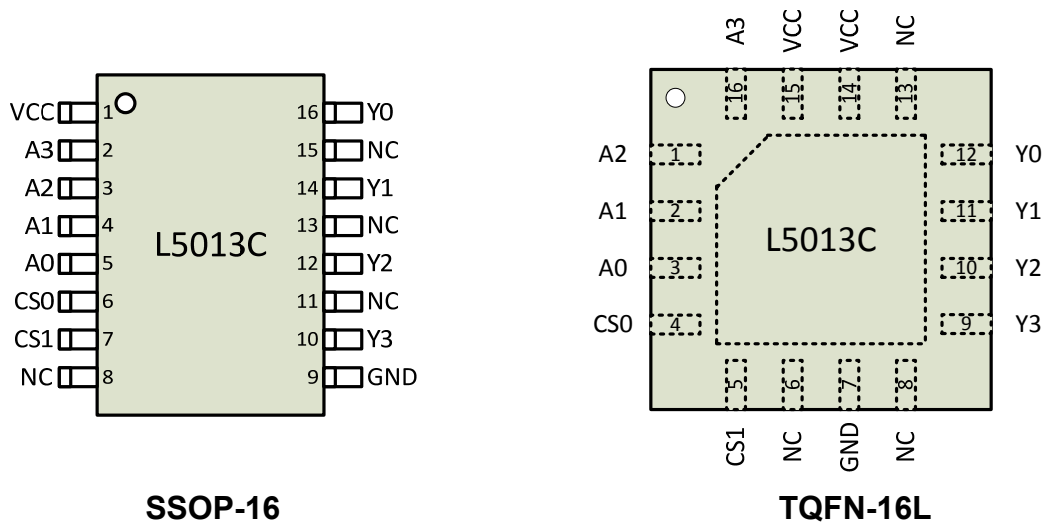
**Applications**

- Outdoor LED Video Displays
- Indoor LED Video Displays
- Variable Message Signs
- Gaming Features

**Simplified Application Circuit**



**Pin configuration**



**Pin Descriptions**

Pin Name	Description	I/O
Vcc	Voltage supply input	Power
A0	Input ,address bus 0	Input
A1	Input ,address bus 1	Input
A2	Input ,address bus 2	Input
A3	Input ,address bus 3	Input
CS0	A2 Logic option	Input
CS1	A3 Logic option	Input
GND	Ground	GND
Y0	Output 0	Output
Y1	Output 1	Output
Y2	Output 2	Output
Y3	Output 3	Output

## Ordering and Marking Information

<p>L5013C</p> <p>Assembly Material Handling Code Temperature Range Package Code</p>	<p>Package Code N : SSOP – 16 QB : TQFN – 16 Operating Ambient Temperature Range I : - 40 to 85 Handling Code TR Tap &amp; Reel Assembly Material G : Halogen and Lead Free Device</p>
<p>L5013CN :</p>	<p>XXXXX - Date Code</p>
<p>L5013CQB :</p>	<p>XXXXX - Date Code</p>

Note: Supec lead-free products contain molding compounds/die attach materials and 100% matte tin plate termination finish; which are fully compliant with RoHS and compatible with both SnPb and lead-free soldering operations. Anpec lead-free products meet or exceed the leadfree requirements of IPC/JEDEC J STD-020C for MSL classification at lead-free peak reflow temperature.

### Absolute Maximum Ratings (Note 1)

Symbol	Parameter	Rating	Unit
V <sub>CC</sub>	VCC Supply Voltage (VCC to GND)	-0.3 ~ 6	V
V <sub>out</sub>	Output Pin to GND Voltage	-0.3 ~ V <sub>CC</sub>	V
I <sub>out</sub>	Output Current	6	A
P <sub>D</sub>	Maximum Power Dissipation	SSOP-16	W
		TQFN3×3-16	
T <sub>J</sub>	Maximum Junction Temperature	-40~150	°C
T <sub>STG</sub>	Storage Temperature	-65 ~ 150	°C
T <sub>SDR</sub>	Maximum Lead Soldering Temperature(10 Seconds)	260	°C
V <sub>ESD</sub>	Minimum ESD Rating(Human Body Mode)	2	KV

Note 1: Absolute Maximum Ratings are those values beyond which the life of a device may be impaired. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

## Thermal Characteristics (Note 2)

Symbol	Parameter	Typical Value	Unit
$\theta_{JA}$	Junction-to-Ambient Resistance in free air (Note 2)	SSOP-16	155
		TQFN3×3-16	50

Note 2:  $\theta_{JA}$  is measured with the component mounted on a high effective thermal conductivity test board in free air. The exposed pad of xxxxx is soldered directly on the PCB.

## Recommended Operating Conditions (Note 3)

Symbol	Parameter	Range	Unit
$V_{CC}$	VCC Supply Voltage (VCC to GND)	4.5~5.5	V
$T_A$	Ambient Temperature	-40 ~ 85	°C
$T_J$	Junction Temperature	-40 ~ 125	°C

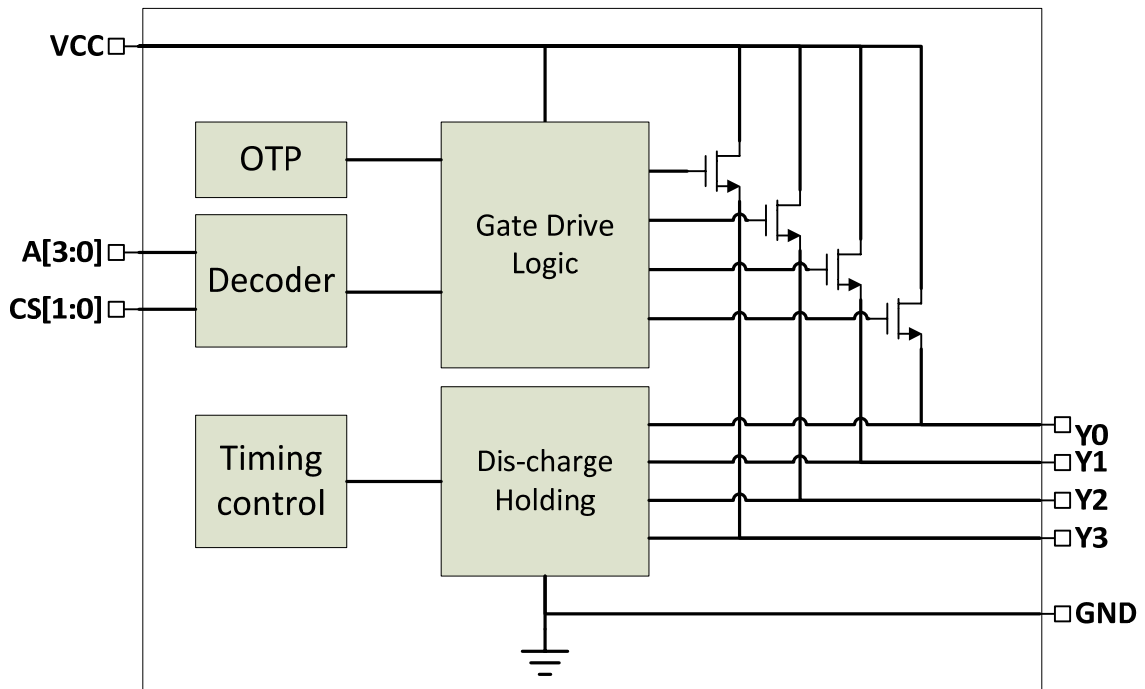
Note 3 : Refer to the typical application circuit

## Electrical Characteristics

Unless otherwise specified, these specifications apply over  $V_{CC}=5V$  and  $T_A = -40 \sim 85$  °C. Typical values are at  $T_A=25$ °C.

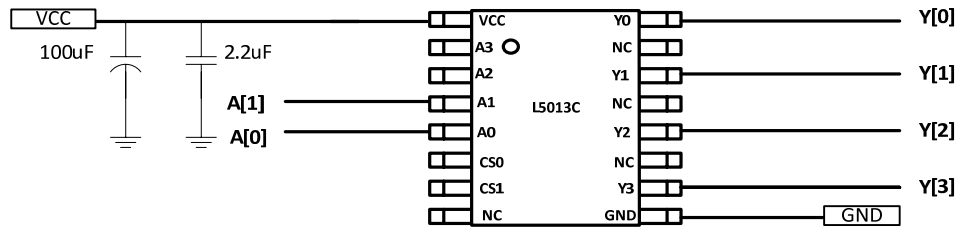
Symbol	Parameter	Test Conditions	SPL5013C			Unit
			Min	Typ	Max	
<b>SUPPLY VOLTAGE AND CURRENT</b>						
$V_{CC}$	Supply Voltage		3	5.0	5.5	V
$I_Q$	Quiescent Current	$V_{CC}=5V$		700	950	uA
<b>POWER SWITCH</b>						
$R_{DS(ON)}$	Power Switch On Resistance	$V_{CC}=5V, I_{OUT-}=1A$		80		mΩ
<b>LOGIC INPUTS(A0 A1 A2 A3 CS0 CS1)</b>						
$V_L$	Input Low Voltage				0.2* $V_{CC}$	V
$V_H$	Input High Voltage		0.8* $V_{CC}$			V
$T_M$	A[3:2]Timing Mismatch to A[1:0]			5		nS
<b>DELAY TIME</b>						
$T_{D(ON)}$	Logic Input to Output Turn On Delay Time			30	35	ns
$T_{D(OFF)}$	Logic Input to Output Turn Off Delay Time			30	35	ns
<b>OUTPUT RISE / FALL TIME</b>						
$T_{R\_OUT}$	Output Rise Time	$V_{CC}=5V, C_{-OUT-}=0, I_{-OUT-}=0$		30	35	ns
		$V_{CC}=5V, C_{-OUT-}=0, I_{-OUT-}=1A$		60	70	
		$V_{CC}=5V, C_{-OUT-}=0.01uF, I_{-OUT-}=1A$		100	120	
$T_{F\_OUT}$	Output Fall Time	$V_{CC}=5V, C_{-OUT-}=0, I_{-OUT-}=0$			0.1	us
		$V_{CC}=5V, C_{-OUT-}=0.01uF, I_{-OUT-}=1A$			1	
<b>OVERT-TEMPERATURE PROTECTION</b>						
OTP	Over-Temperature Threshold	$T_J$ rising		150		°C
	Over-Temperature Hysteresis			40		°C

Block Diagram



**Typical Application Circuit**

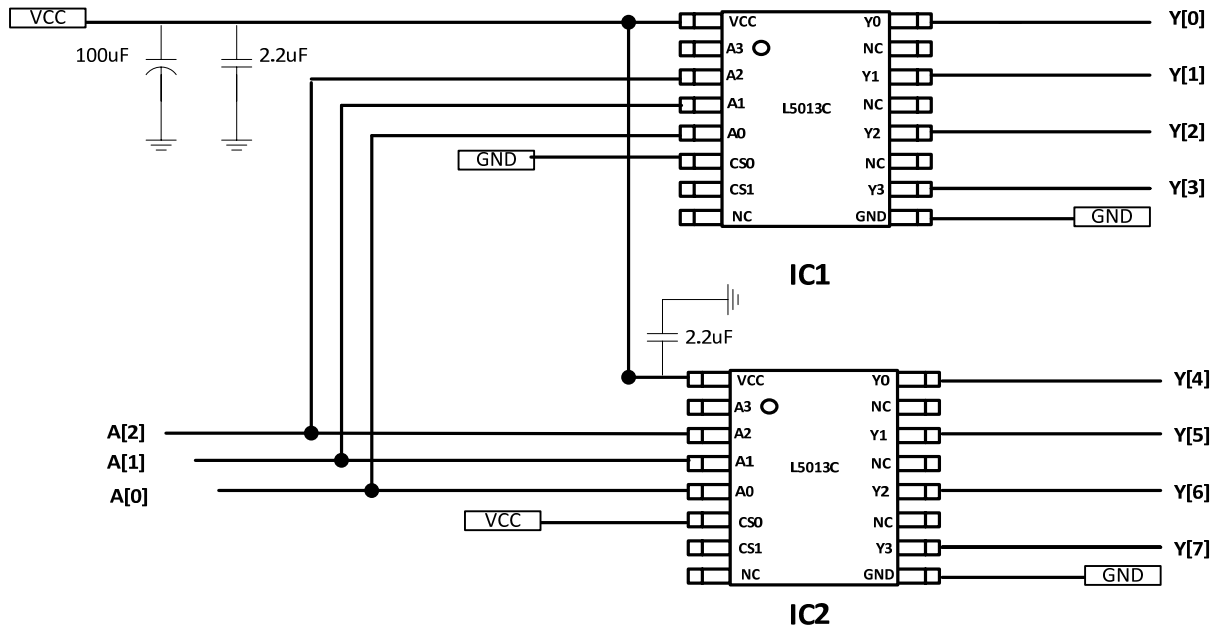
Duty=1/4 application



**True table**

Input		Output			
A[0]	A[1]	Y[0]	Y[1]	Y[2]	Y[3]
0	0	1	0	0	0
1	0	0	1	0	0
0	1	0	0	1	0
1	1	0	0	0	1

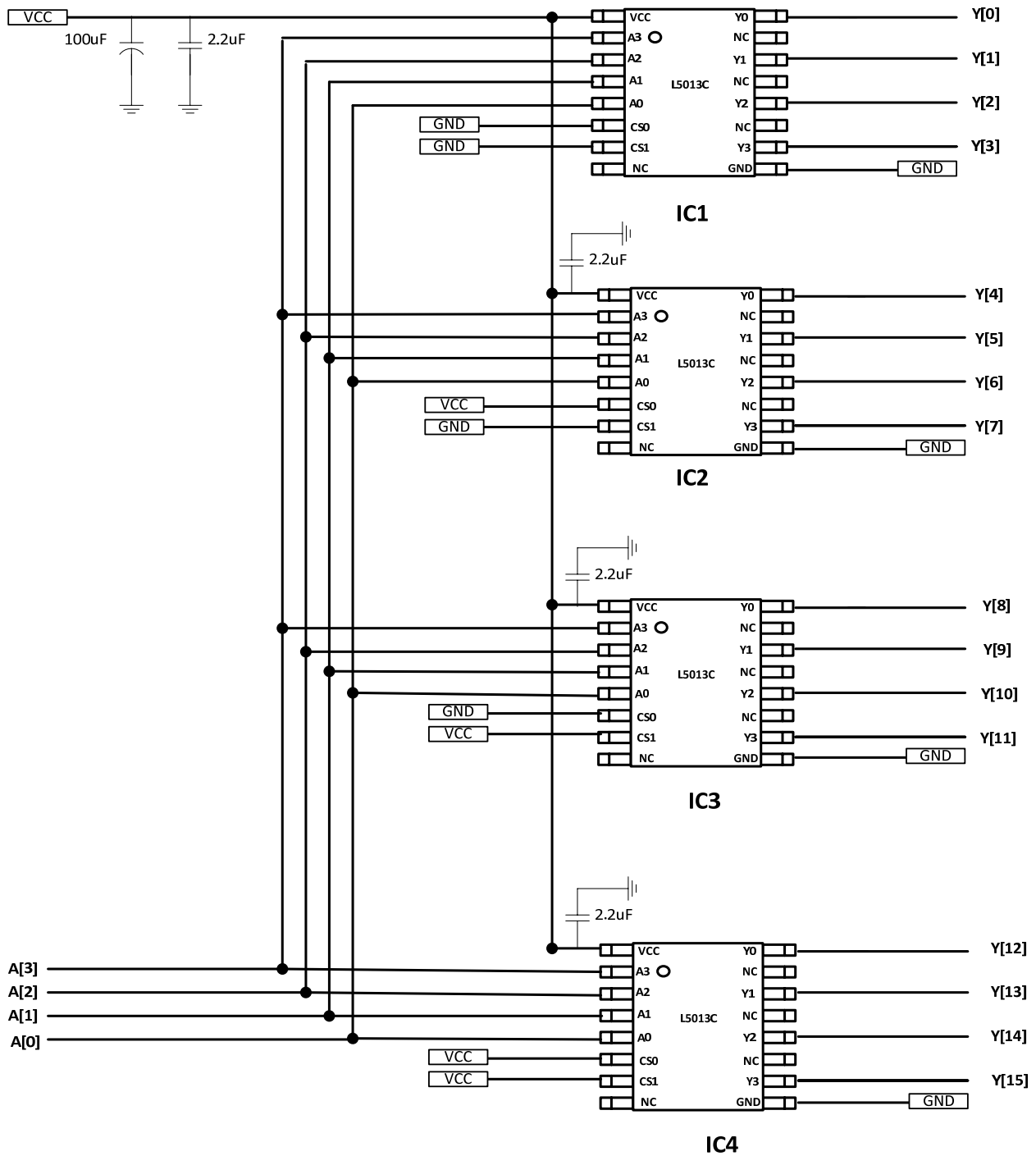
Duty=1/8 application



True table

Input			Output							
A[0]	A[1]	A[2]	Y[0]	Y[1]	Y[2]	Y[3]	Y[4]	Y[5]	Y[6]	Y[7]
0	0	0	1	0	0	0	0	0	0	0
1	0	0	0	1	0	0	0	0	0	0
0	1	0	0	0	1	0	0	0	0	0
1	1	0	0	0	0	1	0	0	0	0
0	0	1	0	0	0	0	1	0	0	0
1	0	1	0	0	0	0	0	1	0	0
0	1	1	0	0	0	0	0	0	1	0
1	1	1	0	0	0	0	0	0	0	1

Duty=1/16 application



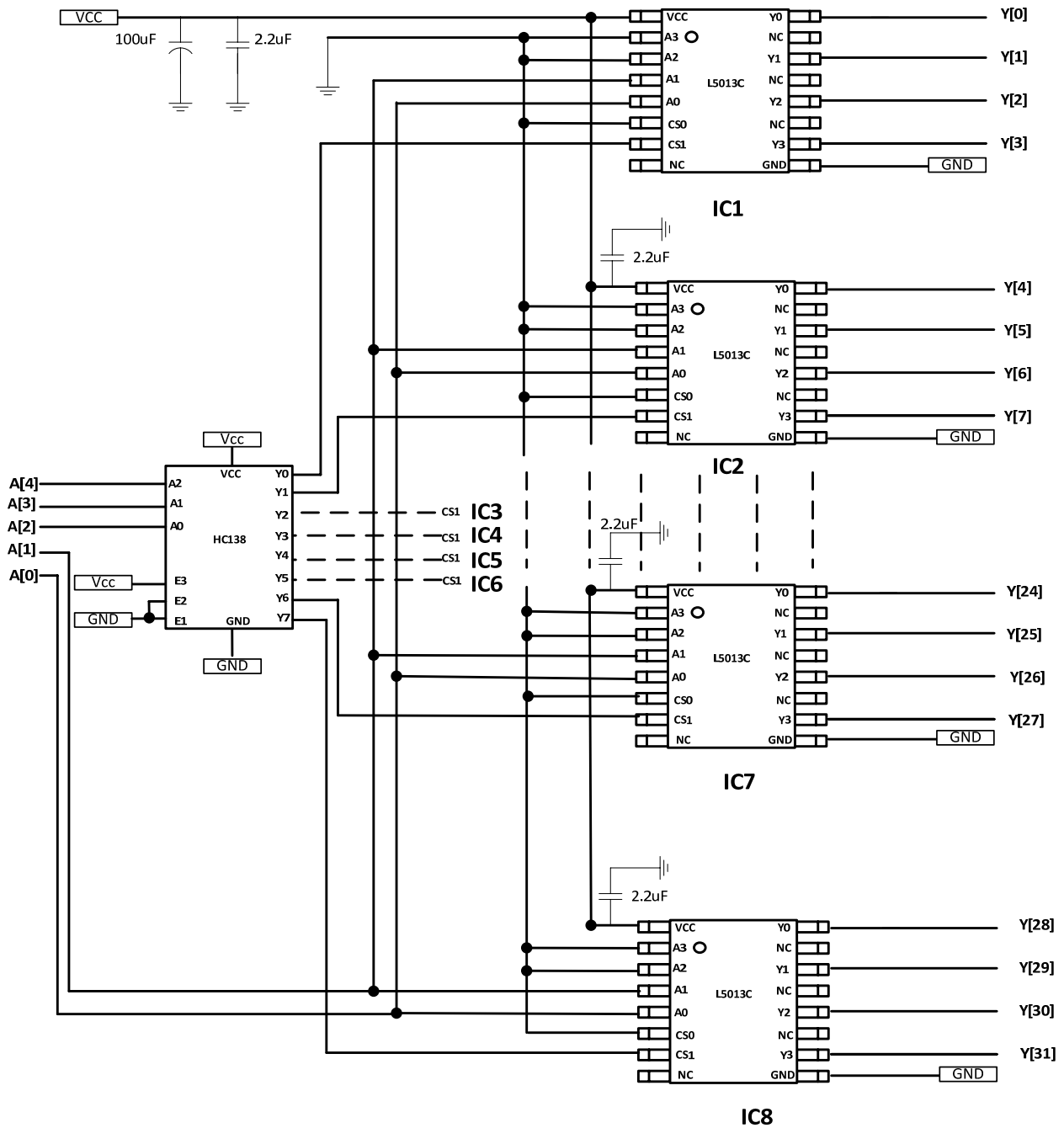


True table

Input				Output							
A[0]	A[1]	A[2]	A[3]	Y[0]	Y[1]	Y[2]	Y[3]	Y[4]	Y[5]	Y[6]	Y[7]
0	0	0	0	1	0	0	0	0	0	0	0
1	0	0	0	0	1	0	0	0	0	0	0
0	1	0	0	0	0	1	0	0	0	0	0
1	1	0	0	0	0	0	1	0	0	0	0
0	0	1	0	0	0	0	0	1	0	0	0
1	0	1	0	0	0	0	0	0	1	0	0
0	1	1	0	0	0	0	0	0	0	1	0
1	1	1	0	0	0	0	0	0	0	0	1
0	0	0	1	0	0	0	0	0	0	0	0
1	0	0	1	0	0	0	0	0	0	0	0
0	1	0	1	0	0	0	0	0	0	0	0
1	1	0	1	0	0	0	0	0	0	0	0
0	0	1	1	0	0	0	0	0	0	0	0
1	0	1	1	0	0	0	0	0	0	0	0
0	1	1	1	0	0	0	0	0	0	0	0
1	1	1	1	0	0	0	0	0	0	0	0

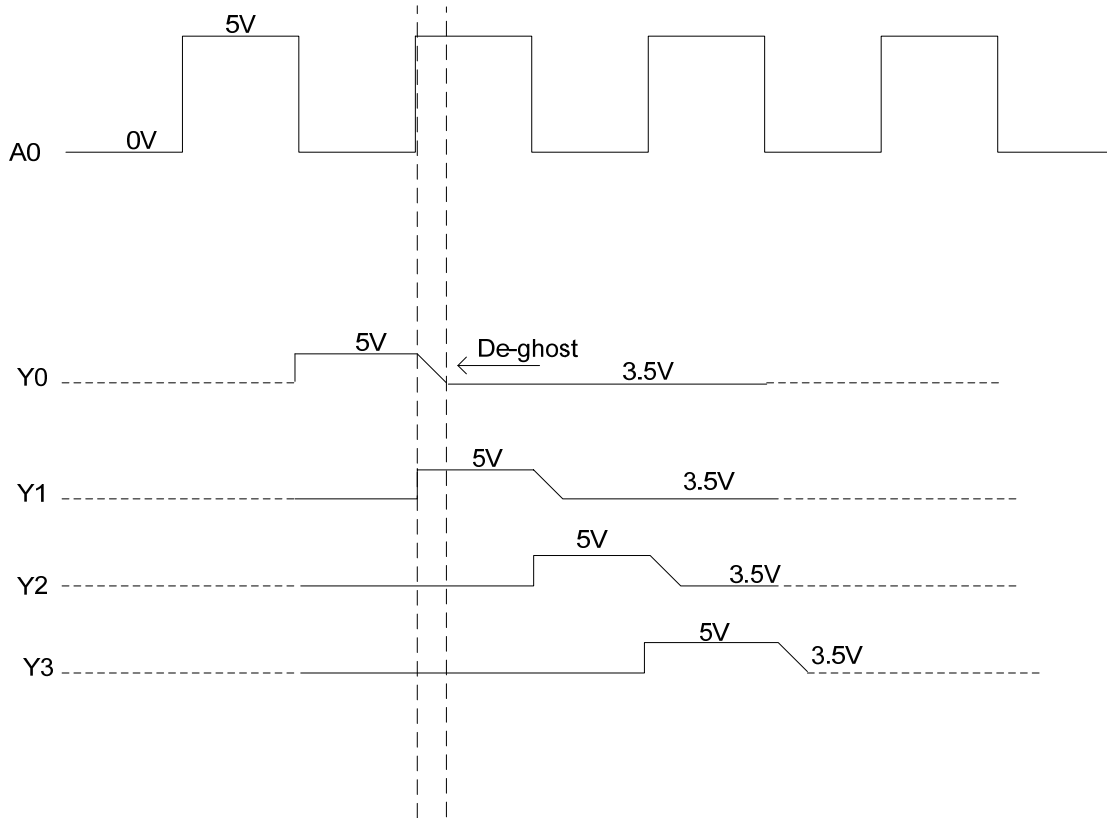
Input				Output							
A[0]	A[1]	A[2]	A[3]	Y[8]	Y[9]	Y[10]	Y[11]	Y[12]	Y[13]	Y[14]	Y[15]
0	0	0	0	0	0	0	0	0	0	0	0
1	0	0	0	0	0	0	0	0	0	0	0
0	1	0	0	0	0	0	0	0	0	0	0
1	1	0	0	0	0	0	0	0	0	0	0
0	0	1	0	0	0	0	0	0	0	0	0
1	0	1	0	0	0	0	0	0	0	0	0
0	1	1	0	0	0	0	0	0	0	0	0
1	1	1	0	0	0	0	0	0	0	0	0
0	0	0	1	1	0	0	0	0	0	0	0
1	0	0	1	0	1	0	0	0	0	0	0
0	1	0	1	0	0	1	0	0	0	0	0
1	1	0	1	0	0	0	1	0	0	0	0
0	0	1	1	0	0	0	0	1	0	0	0
1	0	1	1	0	0	0	0	0	1	0	0
0	1	1	1	0	0	0	0	0	0	1	0
1	1	1	1	0	0	0	0	0	0	0	1

Duty=1/32 application



Application Information

De-ghost Function Descriptions

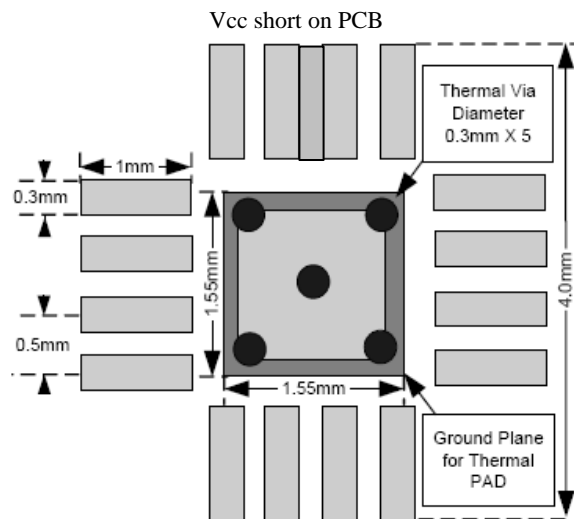
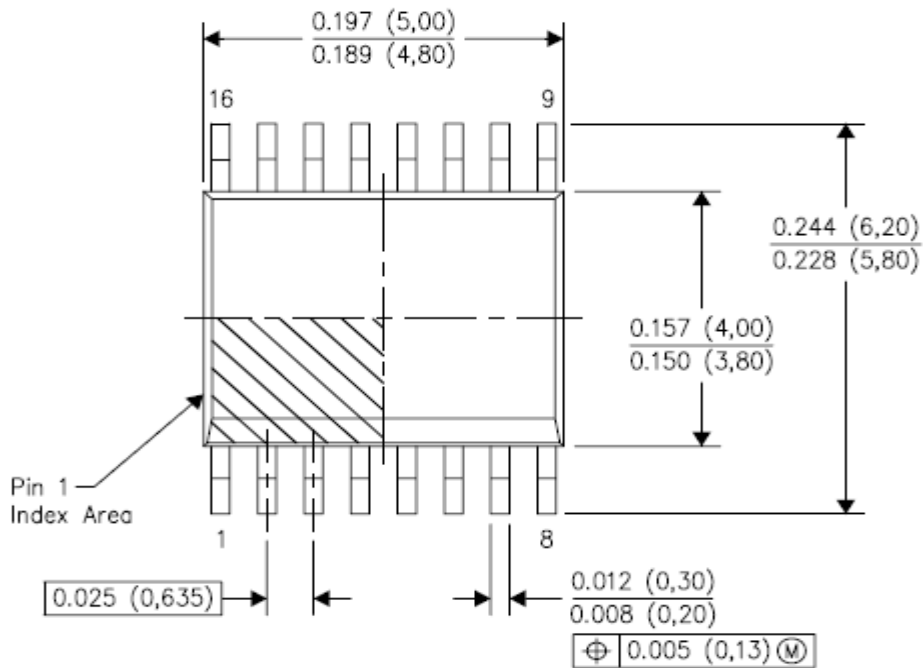


When the output turn off ,it will be De-ghost, the De-ghost level is 70%Vcc

**Layout Guidelines**

- All components should be placed close to the SPL5013C. For example; the input capacitor should be close to SPL5013C's Vcc pins to decouple the power rail noise.
- The output traces should be short, wide (>60mil), symmetric.
- The power trace width should be greater than 60mil.

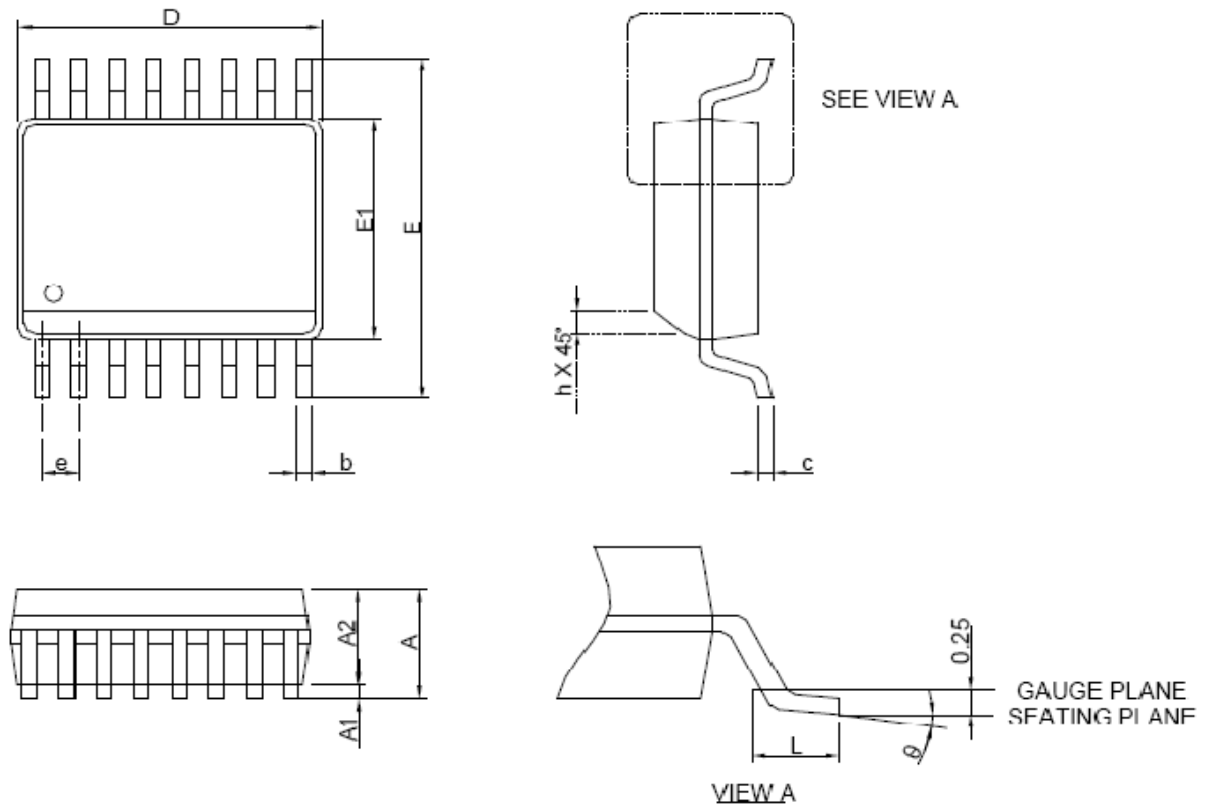
**PCB Drawings**



TQFN3x3-16 Layout Recommendation

Package Information

SSOP-16

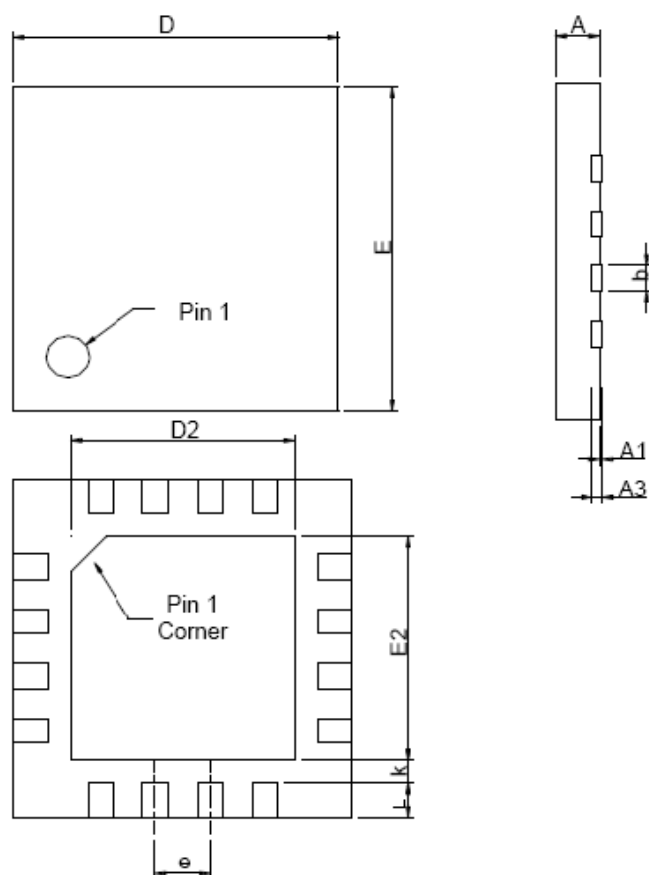


DIMENSIONS	SSOP-16			
	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A		1.75		0.069
A1	0.10	0.25	0.004	0.010
A2	1.24		0.049	
b	0.20	0.30	0.008	0.012
c	0.15	0.25	0.006	0.010
D	4.80	5.00	0.189	0.197
E	5.80	6.20	0.228	0.244
E1	3.80	4.00	0.150	0.157
e	0.635 BSC		0.025 BSC	
L	0.40	1.27	0.016	0.050
h	0.25	0.50	0.010	0.020
θ	0°	8°	0°	8°

- Note : 1. Follow JEDEC MO-13/ AB.  
 2. Dimension "D" does not include mold flash, protrusions or gate burrs. Mold flash, protrusion or gate burrs shall not exceed 6 mil per side.  
 3. Dimension "E" does not include inter-lead flash or protrusions. Inter-lead flash and protrusions shall not exceed 10 mil per side.

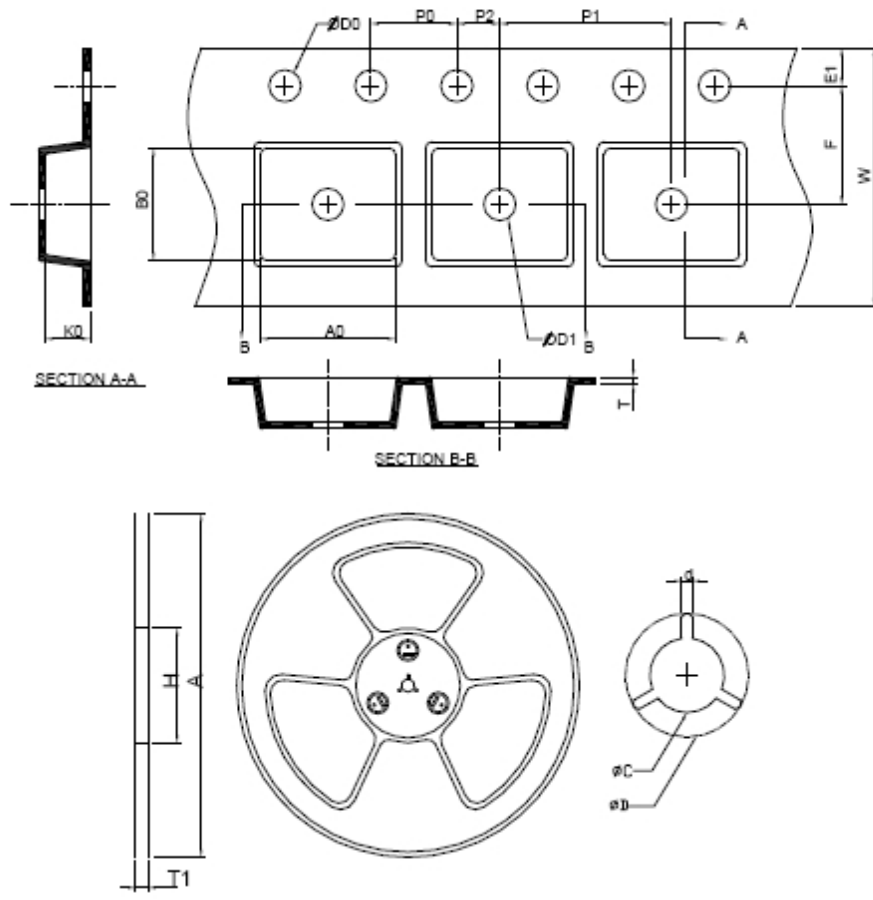
## Package Information

### TQFN3x3-16



SYMBOL	TQFN3x3-16			
	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	0.70	0.80	0.028	0.031
A1	0.00	0.05	0.000	0.002
A3	0.20 REF		0.008 REF	
b	0.18	0.30	0.007	0.012
D	2.90	3.10	0.114	0.122
D2	1.50	1.80	0.059	0.071
E	2.90	3.10	0.114	0.122
E2	1.50	1.80	0.059	0.071
e	0.50 BSC		0.020 BSC	
L	0.30	0.50	0.012	0.020
K	0.20		0.008	

**Carrier Tape & Reel Dimensions**



Application	A	H	T1	C	d	D	W	E1	F
SSOP-16	330.0±2.00	50 MIN.	12.4+2.00 -0.00	13.0+0.50 -0.20	1.5 MIN.	20.2 MIN.	12.0±0.30	1.75±0.10	5.50±0.10
	P0	P1	P2	D0	D1	T	A0	B0	K0
	4.00±0.10	8.00±0.10	2.00±0.05	1.5+0.10 -0.00	1.5 MIN.	0.6+0.00 -0.40	6.40±0.20	5.20±0.20	2.10±0.20

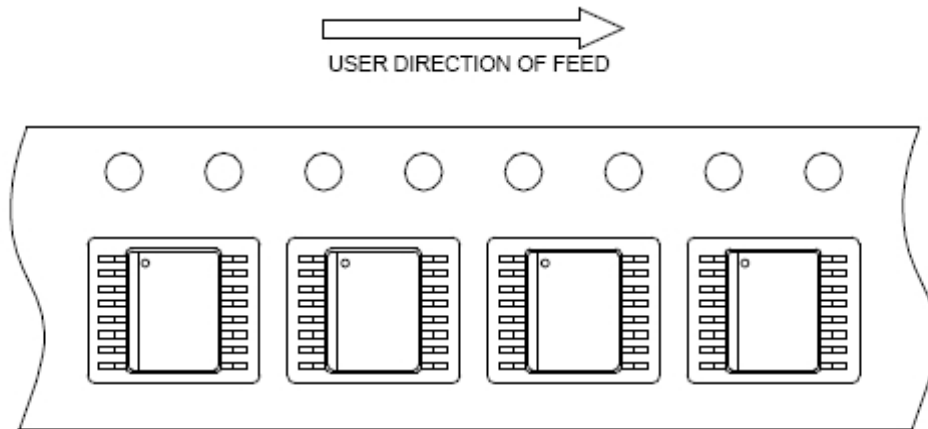
(mm)

**Devices Per Unit**

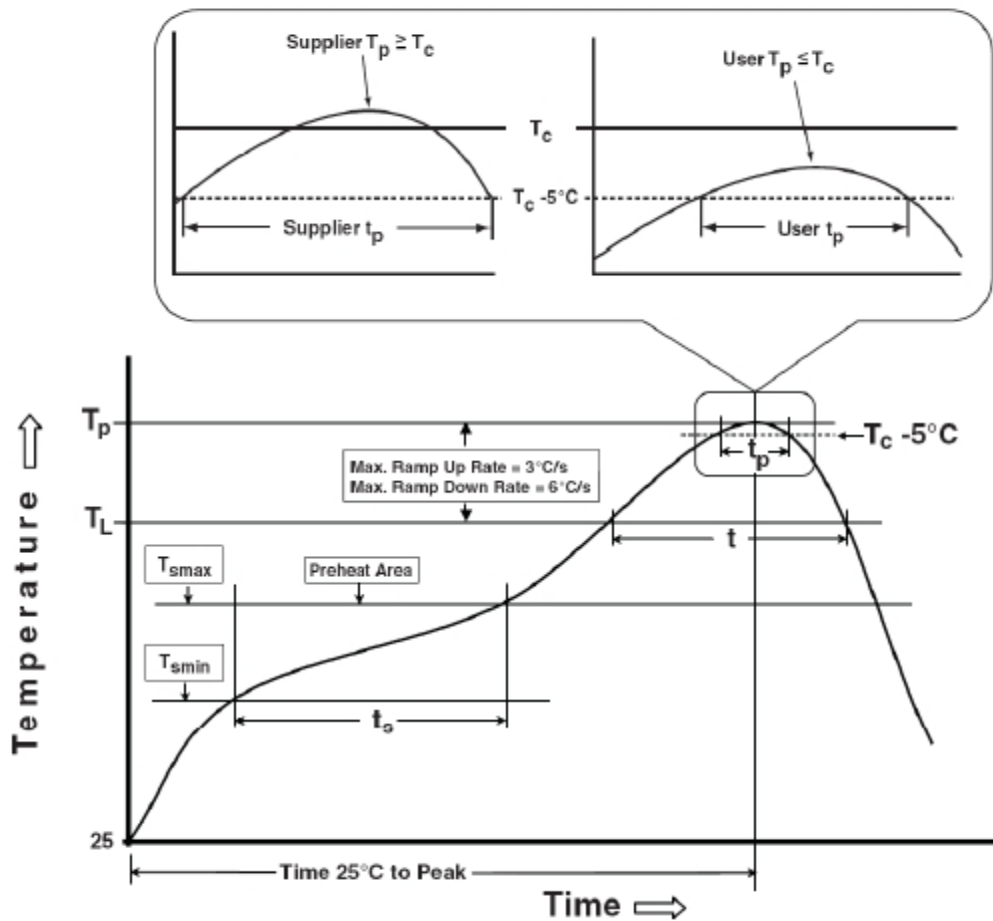
Package Type	Unit	Quantity
SSOP-16	Tape & Reel	2500

## Taping Direction Information

SSOP-16



## Classification Profile





## Classification Reflow Profiles

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
<b>Preheat &amp; Soak</b>		
Temperature min ( $T_{smin}$ )	100 °C	150 °C
Temperature max ( $T_{smax}$ )	150 °C	200 °C
Time ( $T_{smin}$ to $T_{smax}$ ) ( $t_s$ )	60-120 seconds	60-120 seconds
Average ramp-up rate ( $T_{smax}$ to $T_p$ )	3 °C/second max.	3°C/second max.
Liquidous temperature ( $T_L$ )	183 °C	217 °C
Time at liquidous ( $t_L$ )	60-150 seconds	60-150 seconds
Peak package body Temperature ( $T_p$ )*	See Classification Temp in table 1	See Classification Temp in table 2
Time ( $t_p$ )** within 5°C of the specified classification temperature ( $T_c$ )	20** seconds	30** seconds
Average ramp-down rate ( $T_p$ to $T_{smax}$ )	6 °C/second max.	6 °C/second max.
Time 25°C to peak temperature	6 minutes max.	8 minutes max.
* Tolerance for peak profile Temperature ( $T_p$ ) is defined as a supplier minimum and a user maximum.		
** Tolerance for time at peak profile temperature ( $t_p$ ) is defined as a supplier minimum and a user maximum.		

Table 1. SnPb Eutectic Process – Classification Temperatures ( $T_c$ )

Package Thickness	Volume mm <sup>3</sup> <350	Volume mm <sup>3</sup> ≥350
<2.5 mm	235 °C	220 °C
≥2.5 mm	220 °C	220 °C

Table 2. Pb-free Process – Classification Temperatures ( $T_c$ )

Package Thickness	Volume mm <sup>3</sup> <350	Volume mm <sup>3</sup> 350-2000	Volume mm <sup>3</sup> >2000
<1.6 mm	260 °C	260 °C	260 °C
1.6 mm – 2.5 mm	260 °C	250 °C	245 °C
≥2.5 mm	250 °C	245 °C	245 °C

---

**Customer Service**

**Supec (Suzhou) Co., Ltd**

Head Office:

Room C502, 1355 Jinjihu Avenue,  
Suzhou Industrial Park, P.R. China

Tel: 0512-62522212  
Fax: 0512-62522126

Shenzhen Office :

B-701 Hi-Tech Venture Park, Tian'an Cyber Park,  
Futian District, Shenzhen, P.R. China

Tel : 0755-82049356  
Fax : 0755-82049359

## X-ON Electronics

Largest Supplier of Electrical and Electronic Components

*Click to view similar products for [LED Display Drivers](#) category:*

*Click to view products by [Anpec](#) manufacturer:*

Other Similar products are found below :

[STP16DP05PTR](#) [MP3370GN-Z](#) [ISL97631IHTZ-T7A](#) [ISL97632IRT26Z-T](#) [LV5026MC-AH](#) [IK62083DWT](#) [OB3655TAP-H](#) [OB3399PAP](#)  
[AW36514FCR](#) [AW36428FCR](#) [KAQW214A TL](#) [TM1629\(TA2009B\)](#) [WS2814F](#) [XB402U-L27](#) [HT16K33A-20SOP](#) [HT16D33A-28SSOP](#)  
[TM1628E](#) [TM512AE0](#) [TM512AD](#) [TM0822B](#) [SY7310AADC](#) [SY58863FAC](#) [SY5863AJAC](#) [FM4115K](#) [TM1638N-SOP28-TA1319B](#)  
[SPL5013CNI-TRG](#) [AW21024QNR](#) [AW36423FCR](#) [AW36515FCR](#) [AW99703CSR](#) [AW21036QNR](#) [AW21009QNR](#) [AW20108QNR](#)  
[AW2016AQNR](#) [AW9967DNR](#) [PT4115BE89E](#) [CC1108ST](#) [CC1109](#) [SD6800BCTR](#) [SDH7612DH](#) [HT16D35A-48LQFP-EP](#) [HT1635C-](#)  
[64LQFP-7\\*7](#) [HT1632D-52LQFP-2.0](#) [HT16K33A-28SOP](#) [HT16D31A-16NSOP-EP](#) [TLD5099EP](#) [BCR 431U](#) [IS32FL3740-ZLA3-TR](#)  
[PAM2804AAB010\(MS\)](#) [OB3379ZCPA-D](#)